



# TECHNICAL DATA SHEET

## Witcom POM-C-EC-EP-HI, based on Polyoxymethylene Copolymer (POM-C)

conductive, easy moulding, impact modified

Properties	Test methods	Units	POM-C-EC-EP-HI
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### Physical properties

Specific gravity	ISO 1183	g/cm <sup>3</sup>	1,42
Water absorption at saturation, 23 °C	ISO 62	%	0,8
Humidity absorption, 23 °C/50 % r.h.	ISO 62	%	0,2
Mould shrinkage (flow direction, 3 mm)	ISO 2577	%	1,5 - 2,3

### Mechanical properties

Tensile strength (max.) (50 mm/min)	ISO 527	MPa	45
Elongation at break (50 mm/min)	ISO 527	%	>6
Flexural strength	ISO 178	MPa	50
Flexural modulus	ISO 178	GPa	1,8
IZOD impact strength, notched	ISO 180/1eA	kJ/m <sup>2</sup>	6,5
IZOD impact strength, unnotched	ISO 180/1eU	kJ/m <sup>2</sup>	75

### Thermal properties

Heat distortion temperature (1,81 MPa)	ISO 75	°C	105
Relative temperature index, 3 mm, with impact	UL 746B	°C	90
Coefficient of linear thermal expansion	ISO 11359	K·10 <sup>-5</sup>	11,0

### Flammability

Burning behaviour	ISO 1210	-	-
UL recognition	UL94	-	HB @ 0,8 mm

### Electrical properties

Surface resistivity	ASTM D257	Ω/sq	10 <sup>1</sup> - 10 <sup>3</sup>
Comparative tracking index	IEC 60112	V	-
Glow wire rating, 1,6 mm	IEC 695-2-1	°C	-

### Processing conditions (injection moulding)

Drying conditions (dehumidifying drier)	: 2 - 3 Hours @ 80 °C
Maximum allowable moisture content	: 0,05 %
Melt temperature	: 170 - 210 °C
Mould temperature	: 50 - 120 °C
Screw speed	: 0,1 - 0,2 m/s
Back pressure	: 0 - 0,5 MPa
Injection pressure	: Keep to a minimum
Injection speed	: Fast ram speed
Hold pressure	: Keep to a minimum

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